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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



The revision list can be viewed directly by clicking the title page. The revision list summarizes the locations of revisions and additions. Details should always be checked by referring to the relevant text.

SH7720 Group, SH7721 Group

User's Manual: Hardware

Renesas 32-Bit RISC Microcomputer
 SuperH™ RISC engine Family/SH7700 Series

SH7720 Group	HD6417720
	HD6417320
SH7721 Group	R8A77210
	R8A77211

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General Precautions on Handling of Product

1. Treatment of NC Pins

Note: Do not connect anything to the NC pins.

The NC (not connected) pins are either not connected to any of the internal circuitry or are used as test pins or to reduce noise. If something is connected to the NC pins, the operation of the LSI is not guaranteed.

2. Treatment of Unused Input Pins

Note: Fix all unused input pins to high or low level.

Generally, the input pins of CMOS products are high-impedance input pins. If unused pins are in their open states, intermediate levels are induced by noise in the vicinity, a pass-through current flows internally, and a malfunction may occur.

3. Processing before Initialization

Note: When power is first supplied, the product's state is undefined.

The states of internal circuits are undefined until full power is supplied throughout the chip and a low level is input on the reset pin. During the period where the states are undefined, the register settings and the output state of each pin are also undefined. Design your system so that it does not malfunction because of processing while it is in this undefined state. For those products which have a reset function, reset the LSI immediately after the power supply has been turned on.

4. Prohibition of Access to Undefined or Reserved Addresses

Note: Access to undefined or reserved addresses is prohibited.

The undefined or reserved addresses may be used to expand functions, or test registers may have been allocated to these addresses. Do not access these registers; the system's operation is not guaranteed if they are accessed.

Configuration of This Manual

This manual comprises the following items:

1. General Precautions on Handling of Product
2. Configuration of This Manual
3. Preface
4. Contents
5. Overview
6. Description of Functional Modules

- CPU and System-Control Modules
- On-Chip Peripheral Modules

The configuration of the functional description of each module differs according to the module. However, the generic style includes the following items:

- i) Feature
- ii) Input/Output Pin
- iii) Register Description
- iv) Operation
- v) Usage Note

When designing an application system that includes this LSI, take notes into account. Each section includes notes in relation to the descriptions given, and usage notes are given, as required, as the final part of each section.

7. List of Registers
8. Electrical Characteristics
9. Appendix
10. Main Revisions for This Edition (only for revised versions)

The list of revisions is a summary of points that have been revised or added to earlier versions. This does not include all of the revised contents. For details, see the actual locations in this manual.

11. Index

Preface

The SH7720 or SH7721 Group RISC (Reduced Instruction Set Computer) microcomputer includes a Renesas original RISC CPU as its core, and the peripheral functions required to configure a system.

Target Users: This manual was written for users who will be using this LSI in the design of application systems. Users of this manual are expected to understand the fundamentals of electrical circuits, logical circuits, and microcomputers.

Objective: This manual was written to explain the hardware functions and electrical characteristics of this LSI to the above users.
Refer to the SH-3/SH-3E/SH3-DSP Software Manual for a detailed description of the instruction set.

Notes on reading this manual:

- Product names
The following products are covered in this manual.

Product Classifications and Abbreviations

Basic Classification	Product Code
SH7720 Group	HD6417720, HD6417320
SH7721 Group	R8A77210, R8A77211

- In order to understand the overall functions of the chip
Read the manual according to the contents. This manual can be roughly categorized into parts on the CPU, system control functions, peripheral functions, and electrical characteristics.
- In order to understand the details of the CPU's functions
Read the SH-3/SH-3E/SH3-DSP Software Manual.

- Rules: Register name: The following notation is used for cases when the same or a similar function, e.g. serial communication, is implemented on more than one channel:
 XXX_N (XXX is the register name and N is the channel number)
- Bit order: The MSB (most significant bit) is on the left and the LSB (least significant bit) is on the right.
- Number notation: Binary is B'xx, hexadecimal is H'xxxx, decimal is xxxx.
- Signal notation: An overbar is added to a low-active signal: $\overline{\text{xxxx}}$

Related Manuals: The latest versions of all related manuals are available from our web site. Please ensure you have the latest versions of all documents you require.
<http://www.renesas.com/>

SH7720 or SH7721 Group manuals:

Document Title	Document No.
SH7720/SH7721 Group Hardware Manual	This manual
SH-3/SH-3E/SH3-DSP Software Manual	REJ09B0317

Users manuals for development tools:

Document Title	Document No.
Super™ RISC engine C/C++ Compiler, Assembler, Optimizing Linkage Editor Compiler Package V.9.00 User's Manual	REJ10B0152
SuperH™ RISC engine High-performance Embedded Workshop 3 User's Manual	REJ10B0025
SuperH™ RISC engine High-performance Embedded Workshop 3 Tutorial	REJ10B0023

Application note:

Document Title	Document No.
SuperH™ RISC engine C/C++ Compiler Package Application Note	REJ05B0463

Abbreviations

ADC	Analog to Digital Converter
ALU	Arithmetic Logic Unit
ASE	Adaptive System Evaluator
ASID	Address Space Identifier
AUD	Advanced User Debugger
BCD	Binary Coded Decimal
bps	bit per second
BSC	Bus State Controller
CCN	Cache memory Controller
CMT	Compare Match Timer
CPG	Clock Pulse Generator
CPU	Central Processing Unit
DES	Data Encryption Standard
DMAC	Direct Memory Access Controller
etu	Elementary Time Unit
FIFO	First-In First-Out
Hi-Z	High Impedance
H-UDI	User Debugging Interface
INTC	Interrupt Controller
IrDA	Infrared Data Association
JTAG	Joint Test Action Group
LQFP	Low Profile QFP
LRU	Least Recently Used
LSB	Least Significant Bit
MMU	Memory Management Unit
MPX	Multiplex
MSB	Most Significant Bit
PC	Program Counter
PFC	Pin Function Controller
PLL	Phase Locked Loop
PWM	Pulse Width Modulation
RAM	Random Access Memory
RISC	Reduced Instruction Set Computer

ROM	Read Only Memory
RSA	Rivest Shamir Adleman
RTC	Real Time Clock
SCIF	Serial Communication Interface with FIFO
SDHI	SD Host Interface
SDRAM	Synchronous DRAM
SSL	Secure Socket Layer
TAP	Test Access Port
T.B.D	To Be Determined
TLB	Translation Lookaside Buffer
TMU	Timer Unit
TPU	Timer Pulse Unit
UART	Universal Asynchronous Receiver/Transmitter
UBC	User Break Controller
USB	Universal Serial Bus
WDT	Watchdog Timer

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